

ABSTRACT OF THE DISCLOSURE

The apparatus and method of the present invention relates use a dry atmosphere in the component storage portion of the surface mount device placement machine. The dry atmosphere provides the benefit of eliminating the baking process and other moisture management issues. In accordance with one aspect of the present invention, a component placement machine for placing components on printed circuit boards includes a component storage area, a component placement system for taking components from the component storage area and placing the components on the printed circuit boards, an enclosure surrounding the component storage area, and a dry gas delivery system for delivery of a dry gas to the storage area to prevent moisture from being absorbed by the components.